

ABSTRACT

A method of producing plural device chips from a thin plate of a pyroelectric material comprises the following steps. First, plural device-forming regions each having an electrode and a circuit pattern for electrically connecting the electrodes are formed on each of front and rear surfaces of the thin plate to obtain a device substrate. By making an electrical connection between the circuit patterns, and grounding it, all of the device-forming regions on the device substrate are at the same potential. Next, a blast treatment is performed to the device substrate to remove a required region of the pyroelectric material, while leaving a bridge portion extending between adjacent device-forming regions and having the circuit patterns thereon, so that a device-chip aggregate is formed, in which adjacent device chips are coupled through the bridge portion. Subsequently, by removing the bridge portion, the device chip is separated from the device-chip aggregate.